



**SDI Review Form 1.6**

Journal Name:	<a href="#">Journal of Engineering Research and Reports</a>
Manuscript Number:	Ms_JERR_60227
Title of the Manuscript:	Upgrading Die Attach Machine Capability for Micro Electromechanical Systems Package
Type of the Article	Short Research Article

**General guideline for Peer Review process:**

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/journal/10/editorial-policy> )

**PART 1: Review Comments**

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
<b>Compulsory</b> REVISION comments	-	
<b>Minor</b> REVISION comments	The process of die placement and die orientation is well explained.  Brief information about the microfabrication and a comparison with the existing process can be emphasized in more detail.	
<b>Optional/General</b> comments	Clarity of images can be enhanced. Can look at few more references that would help the reader get more information	

**PART 2:**

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
<b>Are there ethical issues in this manuscript?</b>	<i>(If yes, Kindly please write down the ethical issues here in details)</i>	

**Reviewer Details:**

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